ABSTRACT

A wafer W is supported on the rear surface side thereof by a ring frame R by means of a dicing tape T, and a protection tape H is stuck on the front surface side the wafer W. A suction unit 12 includes a table 16 having a suction face 15 in the upper face. The suction face 15 sucks the dicing tape T to hold the wafer W through performing a predetermined suction. At least in a partial area along the periphery of the suction face 15, a groove 24 is formed. By sucking through the suction face 15, the inside of the groove 24 becomes negative pressure and the dicing tape T is sunk therein.